

## IGBT<sup>3</sup> Chip

### FEATURES:

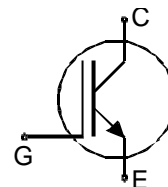
- 600V Trench & Field Stop technology
- low  $V_{CE(sat)}$
- low turn-off losses
- short tail current
- positive temperature coefficient
- easy paralleling

### This chip is used for:

- power module

### Applications:

- drives



Chip Type	$V_{CE}$	$I_{Cn}$	Die Size	Package	Ordering Code
SIGC54T60R3	600V	100A	5.97 x 8.97 mm <sup>2</sup>	sawn on foil	Q67050-A4341-A101

### MECHANICAL PARAMETER:

Raster size	5.97 x 8.97	mm <sup>2</sup>
Emitter pad size	( 2.489 x 1.767 ) x 4 ( 2.789 x 1.995 ) x 4	
Gate pad size	1.615 x 0.817	
Area total / active	53.6 / 40	mm <sup>2</sup>
Thickness	70	μm
Wafer size	150	mm
Flat position	90	deg
Max. possible chips per wafer	245 pcs	
Passivation frontside	Photoimide	
Emitter metallization	3200 nm AlSiCu	
Collector metallization	1400 nm Ni Ag –system suitable for epoxy and soft solder die bonding	
Die bond	electrically conductive glue or solder	
Wire bond	Al, <500μm	
Reject ink dot size	Ø 0.65mm ; max 1.2mm	
Recommended storage environment	store in original container, in dry nitrogen, < 6 month at an ambient temperature of 23°C	

## MAXIMUM RATINGS:

Parameter	Symbol	Value	Unit
Collector-emitter voltage, $T_j=25\text{ °C}$	$V_{CE}$	600	V
DC collector current, limited by $T_{jmax}$	$I_C$	<sup>1)</sup>	A
Pulsed collector current, $t_p$ limited by $T_{jmax}$	$I_{cpuls}$	300	A
Gate emitter voltage	$V_{GE}$	$\pm 20$	V
Operating junction and storage temperature	$T_j, T_{stg}$	-40 ... +175	°C
SC data, $V_{GE} = 15V$ , $V_{CC} = 360V$ , $T_vj = 150\text{ °C}$	$t_p$	5	$\mu s$

<sup>1)</sup> depending on thermal properties of assembly

## STATIC CHARACTERISTICS (tested on chip), $T_j=25\text{ °C}$ , unless otherwise specified

Parameter	Symbol	Conditions	Value			Unit
			min.	typ.	max.	
Collector-emitter breakdown voltage	$V_{(BR)CES}$	$V_{GE}=0V$ , $I_C=4mA$	600			V
Collector-emitter saturation voltage	$V_{CE(sat)}$	$V_{GE}=15V$ , $I_C=100A$	1.05	1.45	1.85	
Gate-emitter threshold voltage	$V_{GE(th)}$	$I_C=1600\mu A$ , $V_{GE}=V_{CE}$	tbd	5.8	tbd	
Zero gate voltage collector current	$I_{CES}$	$V_{CE}=600V$ , $V_{GE}=0V$			270	$\mu A$
Gate-emitter leakage current	$I_{GES}$	$V_{CE}=0V$ , $V_{GE}=20V$			600	nA
Integrated gate resistor	$R_{Gint}$			2		$\Omega$

## ELECTRICAL CHARACTERISTICS (verified by design/characterization):

Parameter	Symbol	Conditions	Value			Unit
			min.	typ.	max.	
Input capacitance	$C_{iss}$	$V_{CE}=25V$ , $V_{GE}=0V$ , $f=1MHz$		tbd		nF
Output capacitance	$C_{oss}$			tbd		
Reverse transfer capacitance	$C_{rss}$			tbd		

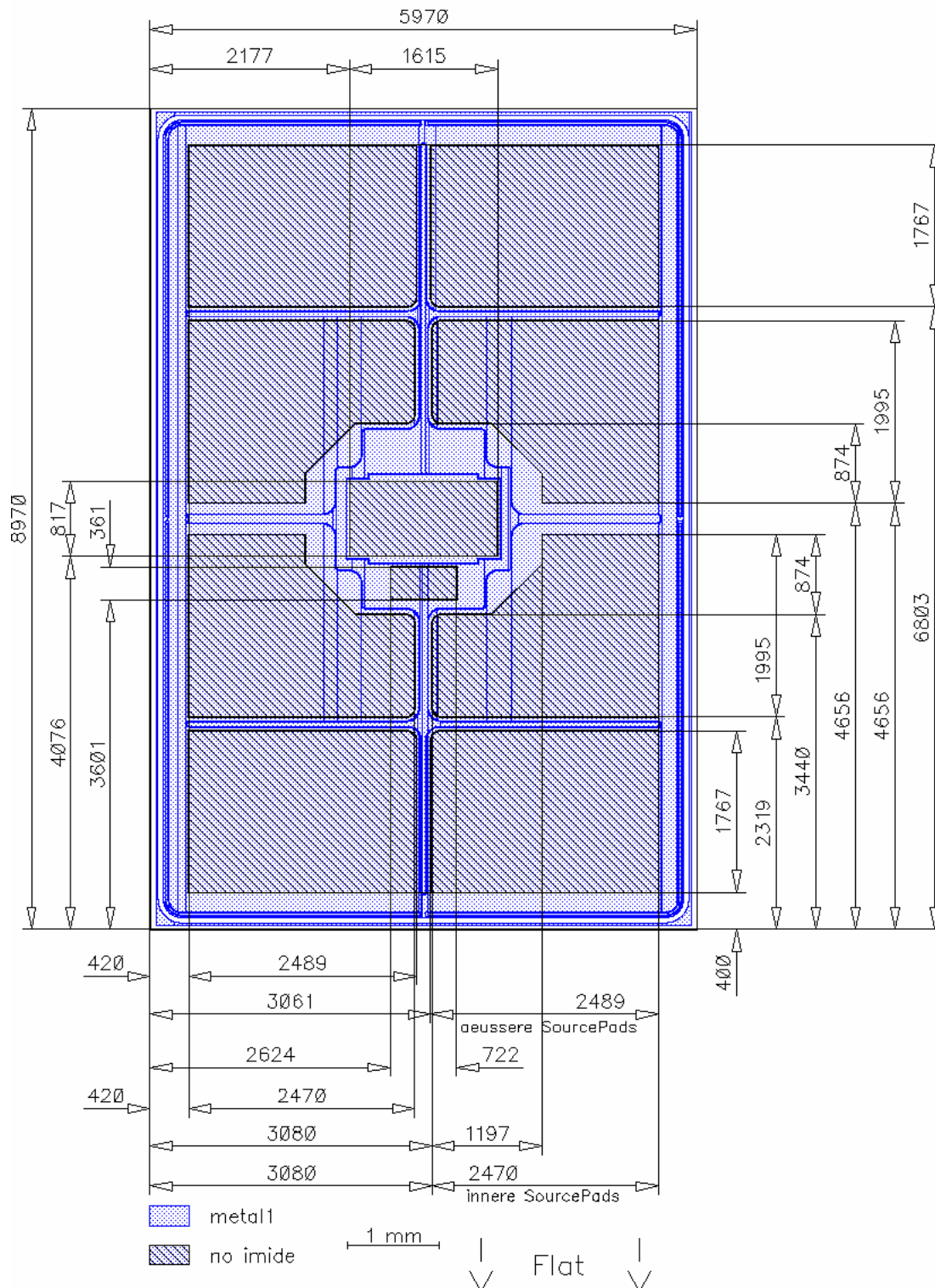
## SWITCHING CHARACTERISTICS (verified by design/characterization), inductive load

Parameter	Symbol	Conditions	Value <sup>2)</sup>			Unit
			min.	typ.	max.	
Turn-on delay time	$t_{d(on)}$	$T_j=125\text{ °C}$ $V_{CC}=300V$ , $I_C=100A$ , $V_{GE}=-15/15V$ , $R_G=tb d\Omega$		tbd		ns
Rise time	$t_r$			tbd		
Turn-off delay time	$t_{d(off)}$			tbd		
Fall time	$t_f$			tbd		

<sup>2)</sup> values also influenced by parasitic L- and C- in measurement and package.

## CHIP DRAWING:

Die-Size 5970 um x 8970 um



**FURTHER ELECTRICAL CHARACTERISTICS:**

This chip data sheet refers to the device data sheet	tbd	
--	-----	--

**DESCRIPTION:**

AQL 0,65 for visual inspection according to failure catalog

Electrostatic Discharge Sensitive Device according to MIL-STD 883

Test-Normen Villach/Prüffeld

**Published by**  
**Infineon Technologies AG,**  
**Bereich Kommunikation**  
**St.-Martin-Strasse 53,**  
**D-81541 München**  
**© Infineon Technologies AG 2004**  
**All Rights Reserved.**

**Attention please!**

The information herein is given to describe certain components and shall not be considered as warranted characteristics.

Terms of delivery and rights to technical change reserved.

We hereby disclaim any and all warranties, including but not limited to warranties of non-infringement, regarding circuits, descriptions and charts stated herein.

Infineon Technologies is an approved CECC manufacturer.

**Information**

For further information on technology, delivery terms and conditions and prices please contact your nearest Infineon Technologies Office in Germany or our Infineon Technologies Representatives world-wide (see address list).

**Warnings**

Due to technical requirements components may contain dangerous substances. For information on the types in question please contact your nearest Infineon Technologies Office.

Infineon Technologies components may only be used in life-support devices or systems with the express written approval of Infineon Technologies, if a failure of such components can reasonably be expected to cause the failure of that life-support device or system, or to affect the safety or effectiveness of that device or system. Life support devices or systems are intended to be implanted in the human body, or to support and / or maintain and sustain and / or protect human life. If they fail, it is reasonable to assume that the health of the user or other persons may be endangered.